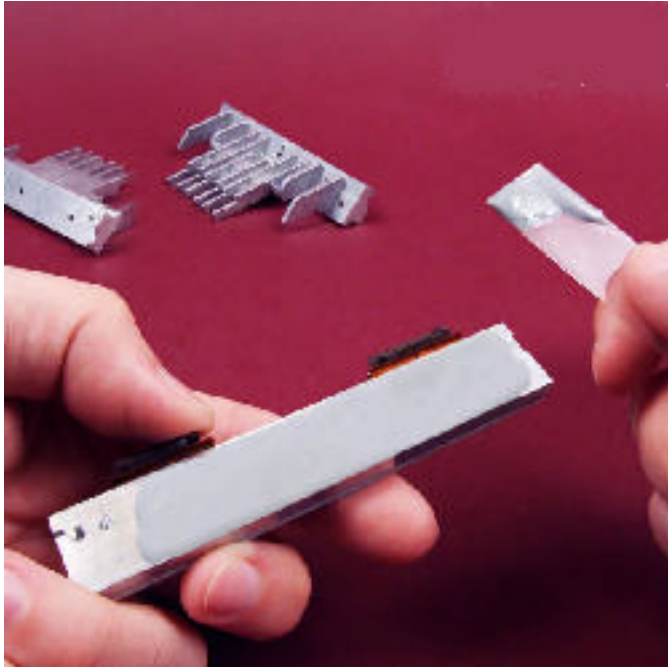


Thermally Conductive Epoxy Delivers High Temperature Resistance



Master Bond has developed a highly thermally conductive epoxy system that is specially designed to help mitigate the issues associated with tightly packed components and miniaturized electronic circuits. With a thermal conductivity over 22 BTU/in/ft²/hr/°F and serviceability from -60 to 400°F, Master Bond EP21ANHT delivers outstanding performance in the most demanding microelectronic applications. The cured adhesive is also a superior electrical insulator, further expanding its usefulness.

This two component adhesive, sealant, and coating has a convenient 1:1 mix ratio by weight or volume and offers room temperature and faster elevated temperature cures. EP21ANHT has a low coefficient of thermal expansion of 18-20 in/in x 10⁻⁶/°C, a dielectric strength of >400 volts/mil, and a tensile shear strength greater than 1,000 psi. It resists a wide range of chemicals and adheres well to a variety of substrates.

EP21ANHT is available in pint, quart, gallon and 5 gallon kits.

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http://www.mdtmag.com/product-releases/2010/12/thermally-conductive-epoxy-delivers-high-temperature-resistance?qt-most_popular=0